

In the Specification:

Please add the following paragraph following the last paragraph on page 10:

5 Preferably, the structural wafer arrangement is thinned to a thickness d which is at most 50 times, and preferably 20 to 30 times as the thickness of the insulating organic connecting layer. Together with the lateral dimensions of the elements defined by structuring the structural wafer arrangement, a predetermined thickness d allows to determine a spring constant of the spring
10 means and the mass of the seismic mass.